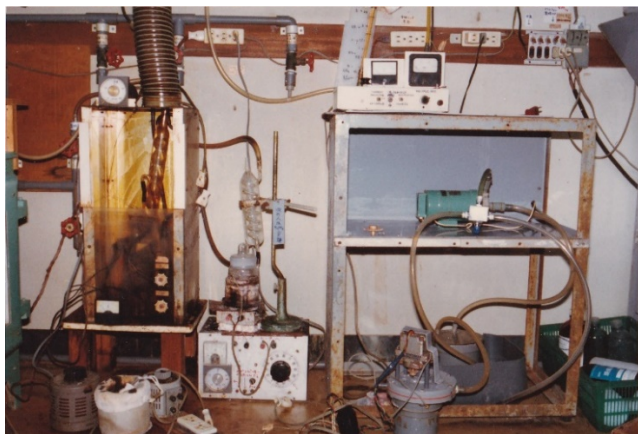
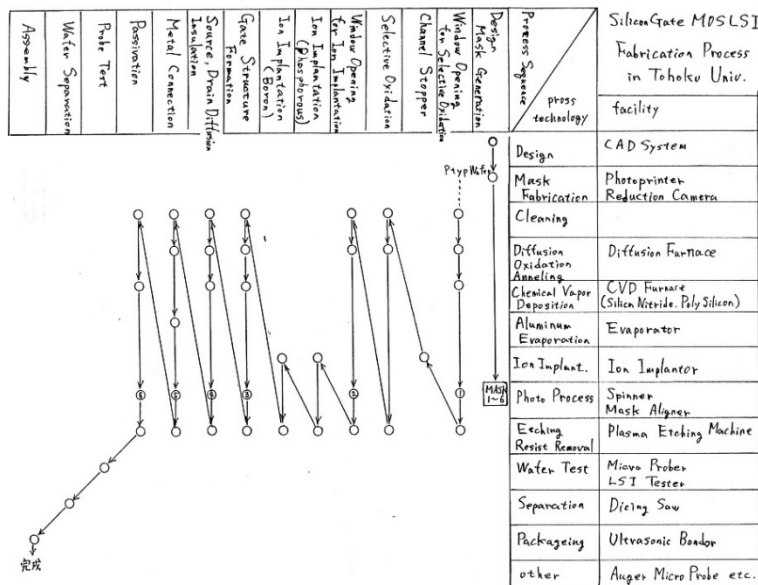
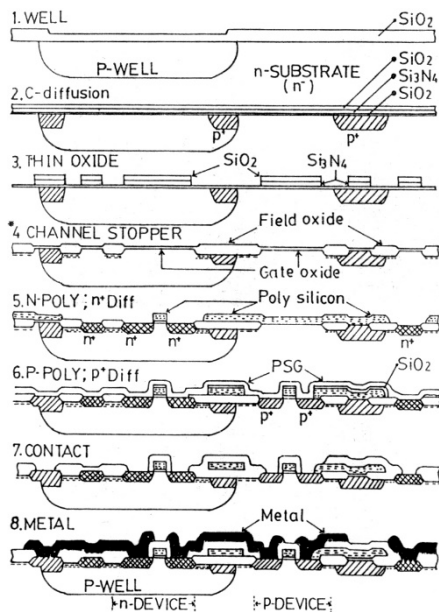
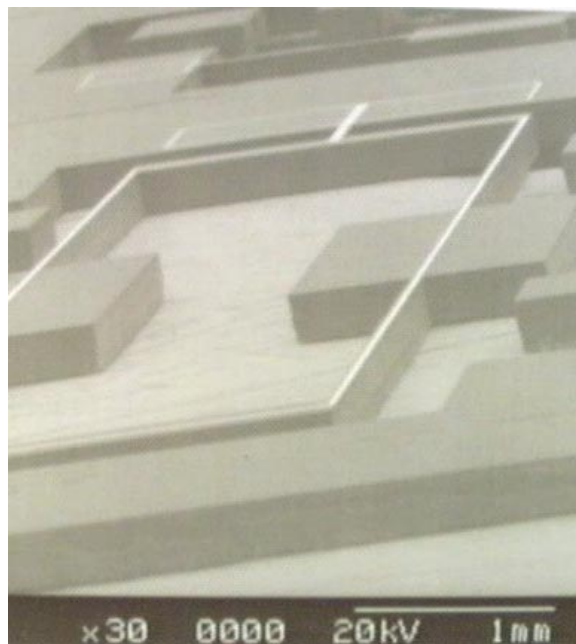
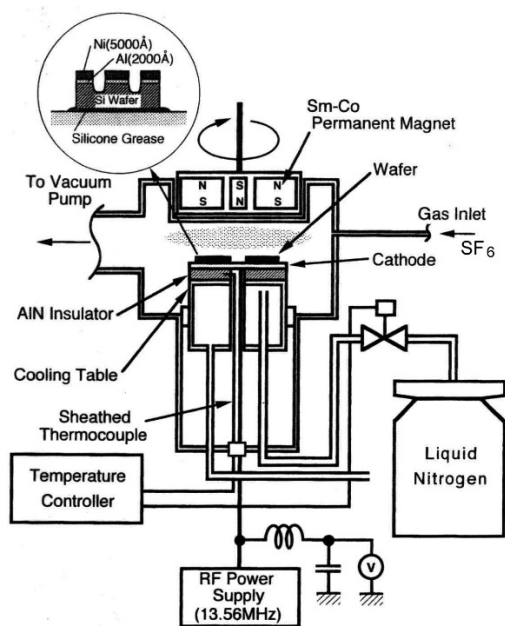


4 Wafer process (1) process sequence, etching



Si EPW etcher, SiN etcher in hot phosphoric acid, Electrochemical Si etcher DI water supply



Si deep RIE (Reactive Ion Etching) system (1992)

Resonating gyroscope by the deep RIE through Si wafer

(M.Takinami, K.Minami and M.Esashi : High-Speed Directional Low-Temp. Dry Etching for Bulk Silicon Micromachining, 11th Sensor Symp. (1992) 15-18)

(J.Choi, K.Minami and M.Esashi : Application of Deep Reactive Ion Etching for Silicon Angular Rate Sensor, Microsystem Tech., 2, 4 (1996) 186-199)